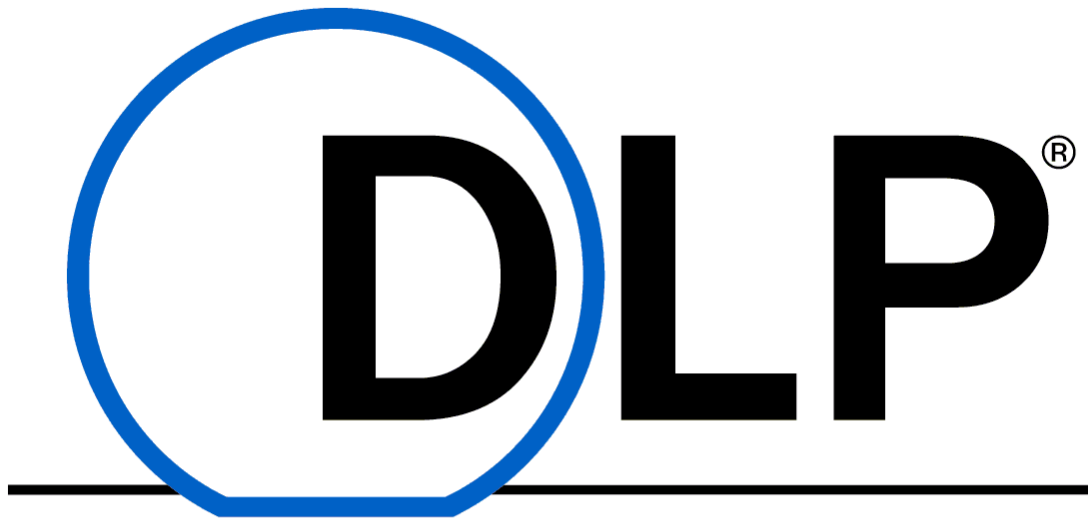


NOTES, UNLESS OTHERWISE SPECIFIED:

- 1. The netname "P5V" represents connection to the +5.0V power buss.
- 2. The netname "P5VA" represents connection to the +5.0V analog reference buss.
- 3. The netname "P12V" represents connection to the +12.0V power buss.
- 4. The symbol ≐ represents connection to the digital ground plane.
- 5. A "Z" suffix on a signal name indicates an active low signal.
- 6. All components with designators "U", "D", "Y" and "Q" are electrostatic discharge sensitive.
- 7. All resistor values are in ohms, 1/16W and 5% unless otherwise specified.



TEXAS INSTRUMENTS

COMPUTER GENERATED DRAWING. DO NOT REVISE MANUALLY			
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2139973: Initial Release	10/22/2013	MM
B	ECO 2139974: Release B	01/03/2014	MM
C	ECO 2139975: Release C	02/17/2014	HPC

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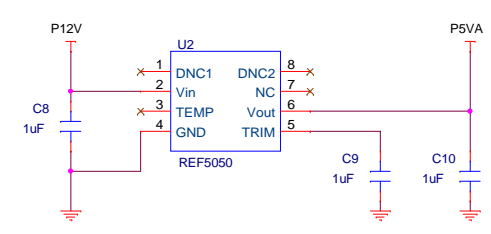
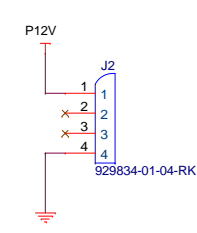
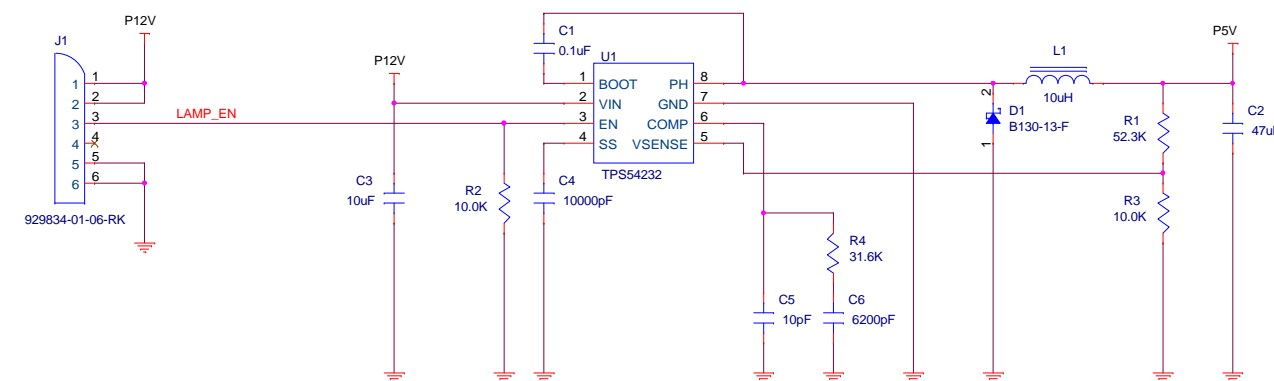
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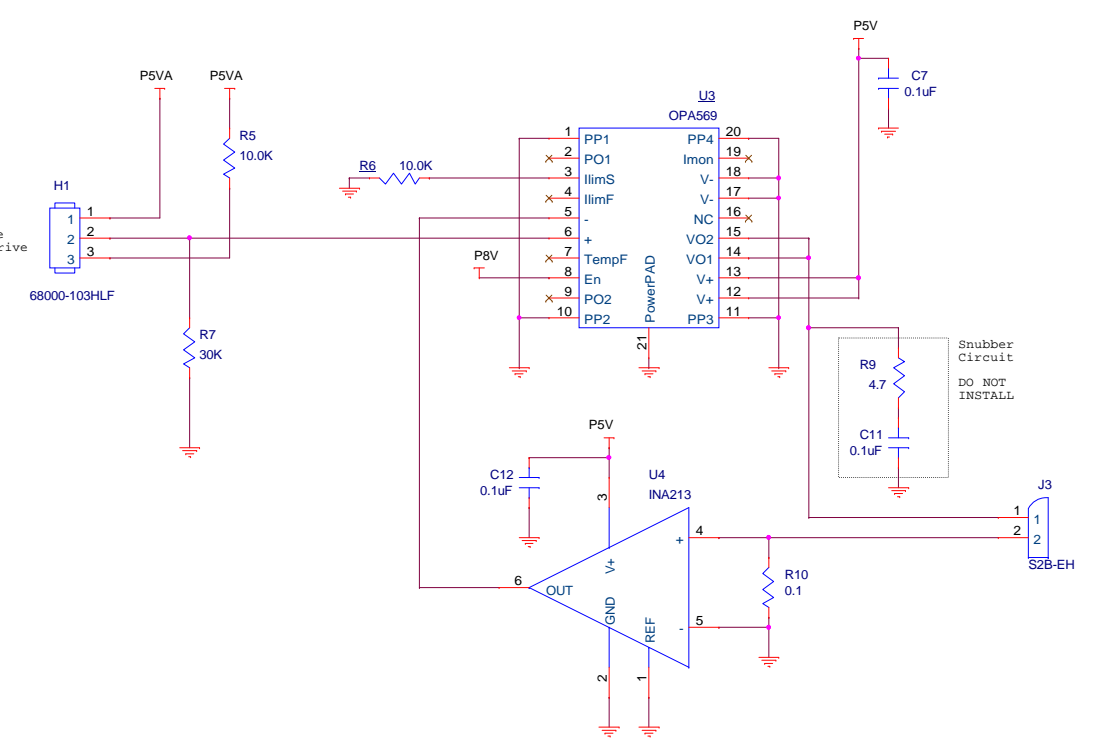
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		ENGR Eric Pruett	10/22/2013			
		APVD Joe Siddall				
		MFG				
2513477	0314CP	QA		TITLE ESD, NIRscan Lamp Driver Board		
NEXT ASSY	USED ON			D	DRAWING NO 2513525	REV C
APPLICATION		SW Allegro Design Entry 16.6		SCALE	SHEET 1 of 3	



Jumper Pins 1&2 for 1A Lamp Drive
Jumper Pins 2&3 for 0.75A Lamp Drive



Revision History	
Rev. A:	ECO 2139973 Initial Release ~ 10/22/2013
Rev. B:	ECO 2139974: Updated output voltage of U1 to 5V; U3 to OPA569 Amplifier ~ 01/03/2014
Rev. C:	ECO 2139975: Up-dated Title block, Notes, Disclamer ~ 02/17/2014

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